

TH 974

Silicone Thermal Adhesive

Description

TH 974 is a white, highly filled silicone system suitable for the screen printing process and thermal dissipation of electronic devices. This one-part system is designed to be heat cured. It has stable pot life and long shelf life even at room temperature of 25oC. It has relatively low viscosity for faster dispense from syringes

Applications

Heat dissipation from electronic components.

Guidelines for Use

1. Thaw the silicone to room temperature (25°C) before use.
2. Dispense the silicone by using a syringe.
3. Wipe off any excess uncured adhesive with a piece of dry cloth or tissue. Further cleaning may be achieved with tissue dabbed with isopropanol.
4. Cure the silicone by heating in a convection oven at 170°C for 10 minutes. Curing at lower temperature will require a longer time.

Recommended Cure

Temp., °C	Time, Min.
170	10

Properties

Property	Test Method	Unit	Typical Value
Chemical type	-	-	Silicone
Appearance	Pen 10	-	White
Shelf life, 25°C	Pen 26	Month	6
Pot life, 25°C	Pen 57	Day	30
Viscosity, Brookfield Cap 2000+, 25°C	Pen 44	cP	60,000
Adhesion strength	Pen 42	kgf	39.7
Hardness	Pen 29	Shore A	65
Thermal conductivity	ISO/DIS 22007	W/mK	1.4
Specific gravity	Pen 14		1.7
Hardness	Pen 29	Shore A	57

Storage

Tightly close original container of unused product. Store in a cool and dark place. Storing at lower temperatures down to -20oC may prolong shelf life beyond 6 months. However it may take longer time to thaw the product.

Packaging & Dimension

- 30 ml EFD syringe
- 300 ml plastic jar
- 1 kg plastic pail

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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